



Material Content Data Sheet



Sales Product Name		IDH08SG60C		Issued		29. August 2013			
MA#		MA000629798							
Package		PG-TO220-2-1		Weight*		1966.16 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.433	0.07	0.07	729	729	
leadframe	non noble metal	iron	7439-89-6	1.343	0.07		683		
	inorganic material	phosphorus	7723-14-0	0.403	0.02		205		
	non noble metal	copper	7440-50-8	1341.263	68.23	68.32	682175	683063	
wire	non noble metal	aluminium	7429-90-5	1.271	0.06	0.06	646	646	
encapsulation	organic material	carbon black	1333-86-4	9.086	0.46		4621		
	plastics	epoxy resin	-	99.950	5.08		50835		
	inorganic material	silicondioxide	60676-86-0	496.723	25.26	30.80	252637	308093	
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7368	7368	
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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